

L Number	Hits	Search Text	DB	Time stamp
3	1178	(TFT\$1 or Thin adj film adj transistor\$1) and (cu or copper) and (ti or titanium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/19 16:14
4	1	JP-02270215-A\$.DID. and ((cu or copper) same (ti or titanium))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/19 16:13
5	1	JP-02270215-A\$.DID. and ((cu or copper) with (ti or titanium))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/19 16:17
6	254	(TFT\$1 or Thin adj film adj transistor\$1) and ((cu or copper) with gate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/19 16:15
7	609	((TFT\$1 or Thin adj film adj transistor\$1) and (cu or copper) and (ti or titanium)) and ((cu or copper) with (ti or titanium))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/19 16:17
8	160	((TFT\$1 or Thin adj film adj transistor\$1) and (cu or copper) and (ti or titanium)) and ((TFT\$1 or Thin adj film adj transistor\$1) and ((cu or copper) with gate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/19 16:17
-	2	jp10153788\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 15:50
-	0	"10-153788"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 15:50
-	2	"10153788"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 16:33
-	2	"53116089"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 16:46
-	3	"06097164"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 16:54
-	0	jp406097164	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 16:55
-	1	jp406097164\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 16:55
-	3	"03152807"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 17:04

-	27417	(cu or copper) near2 (wiring or wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 17:06
-	59	((cu or copper) near2 (wiring or wire)) with coat\$4 with (titanium or Ti or TiO\$5 or "titanium oxide")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 17:17
-	447	((cu or copper) near2 (wiring or wire)) with (titanium or Ti or TiO\$5 or "titanium oxide")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 17:40
-	5	((cu or copper) near2 (wiring or wire)) with (titanium or Ti or TiO\$5 or "titanium oxide")) and (tft\$1 or (thin adj film adj trnasistor\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 17:27
-	9	((cu or copper) near2 (wiring or wire)) with Tin with adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 17:36
-	0	((cu or copper) near2 (wiring or wire)) with (titanium or Ti or TiO\$5 or "titanium oxide")) and (Tin with adhesion) and TFT\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 17:37
-	5	((cu or copper) near2 (wiring or wire)) with (titanium or Ti or TiO\$5 or "titanium oxide")) and Tin and TFT\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 17:37
-	4437	(cu or copper) with coat\$5 with (titanium or Ti or TiO\$5 or "titanium oxide")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/16 17:41
-	15	((cu or copper) with coat\$5 with (titanium or Ti or TiO\$5 or "titanium oxide")) and TFT\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 08:18
-	957	257/59.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 08:18
-	137	257/59.cccls. and (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 10:02
-	137	257/59.cccls. and (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 10:34
-	4	("5998230" "6008065").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 10:29
-	0	6297519.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 10:31

	134	(tft\$1 or (thin adj film adj transistor\$1)) and (copper or cu) and refractory	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 10:55
	32	(tft\$1 or (thin adj film adj transistor\$1)) and ((copper or cu) with refractory)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:53
	142	((copper or cu) with protect\$4 with refractory)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:03
	70	(ti adj (copper or cu) adj ti)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:06
	12450	(electrode\$1 near3 (copper or cu))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:43
	454	(electrode\$1 near3 (copper or cu)) with (ti or titanium or "titianium oxide" or ("tiO.sub. 2"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:11
	4	((electrode\$1 near3 (copper or cu)) with (ti or titanium or "titianium oxide" or ("tiO.sub. 2"))) and (tft\$1 or (thin adj film adj transistor\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:10
	6982	(copper or cu) with (cover\$5 or protect\$5 or coat\$ or laminat\$5 or barrier) with (ti or titanium or "titianium oxide" or ("tiO.sub. 2"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:14
	304	((copper or cu) with (cover\$5 or protect\$5 or coat\$ or laminat\$5 or barrier) with (ti or titanium or "titianium oxide" or ("tiO.sub. 2"))) and display	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:15
	181	((copper or cu) with (cover\$5 or protect\$5 or coat\$ or laminat\$5 or barrier) with (ti or titanium or "titianium oxide" or ("tiO.sub. 2"))) and display) and liquid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:39
	1	JP408248442A	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:39
	2	"08248442"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:43
	84919	(electrode\$1 or wir\$4 or film\$1 or layer\$1) near2 (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 11:50
	205	((electrode\$1 or wir\$4 or film\$1 or layer\$1) near2 (copper or cu)) and ((Ti or titanium) with TiN with ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 13:23

		4	((electrode\$1 or wir\$4 or film\$1 or layer\$1) near2 (copper or cu)) and ((Ti or titanium) with TiN with ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x")) and (tft\$1 or (thin adj film adj transistor\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 11:53
		0	((electrode\$1 or wir\$4 or film\$1 or layer\$1) near2 (copper or cu)) and ((Ti or titanium) with Ti with oxide3 with nitrideN with ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 11:54
		181	((electrode\$1 or wir\$4 or film\$1 or layer\$1) near2 (copper or cu)) and ((Ti or titanium) with Ti with oxide\$1 with nitrid\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 12:16
		23	("4916397" "4933743" "5008730" "5262354" "5374849" "5391906" "5442235" "5592024").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 12:12
		11	"5793112"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 12:16
		1893	(copper or cu) and ((Ti or titanium) with TiN with ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 13:27
		238	((copper or cu) and ((Ti or titanium) with TiN with ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x")) and display	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 13:30
		216	((copper or cu) and ((Ti or titanium) with TiN with ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x")) and (liquid adj crystal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 13:31
		118	((copper or cu) and ((Ti or titanium) with TiN with ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x")) and (liquid adj crystal)) not ((copper or cu) and ((Ti or titanium) with TiN with ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x")) and display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 13:33
		32	((copper or cu) and ((Ti or titanium) with TiN with ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x")) and gate and source and drain	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 13:34
		390	257/762.ccls. and (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 13:41
		242	(257/762.ccls. and (copper or cu)) and ((Ti or titanium) or TiN or ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 13:42
		6	(257/762.ccls. and (copper or cu)) and ((Ti or titanium) and TiN and ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/18 13:45

-	8	(257/762.ccls. and (copper or cu)) and ((Ti or titanium) and ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 13:46
-	26	257/55-75.ccls. and (cu or copper) and ((Ti or titanium) and ("titanium oxide" or "tiO.sub.2" or "Tio.sub.x"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 13:47
-	253	257/55-75.ccls. and (cu or copper) and (ti or titanium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/19 16:10
-	212	438/148-166.ccls. and (cu or copper) and (ti or titanium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 14:05
-	5	345/97.ccls. and (cu or copper) and (ti or titanium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 14:06
-	333	349/39-139.ccls. and (cu or copper) and (ti or titanium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/18 14:07